



SOT226A

plastic single-ended package (I2PAK); TO-262

8 February 2016

Package information

1. Package summary

Terminal position code	S (single)
Package type descriptive code	I2PAK
Package type industry code	I2PAK
Package style descriptive code	SIP (single in-line package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	TO-262
Mounting method type	T (through-hole mount)
Issue date	25-8-2009

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	8.6	-	9	9.4	mm
E	package width	9.65	-	10	10.3	mm
A	seated height	4.3	-	4.5	4.7	mm
e	nominal pitch	-	-	2.54	-	mm
n ₂	actual quantity of termination	-	-	3	-	



2. Package outline

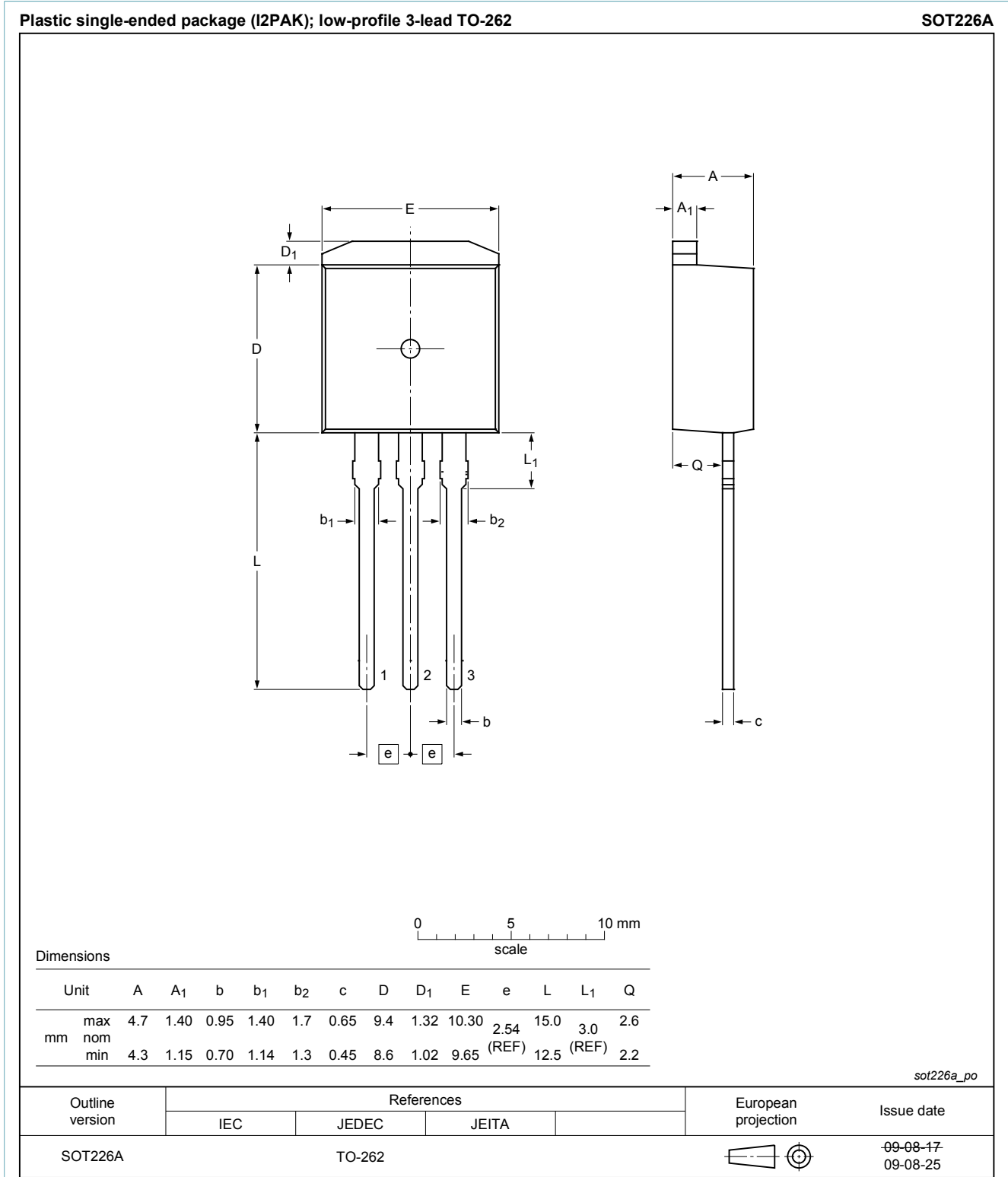


Fig. 1. Package outline I2PAK (SOT226A)

3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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